

PXP400-100QS 100 V, P-channel Trench MOSFET

7 May 2020

## 1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in an MLPAK33 (SOT8002-2) Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

## 2. Features and benefits

- Trench MOSFET technology ٠
- MLPAK33 package (3.3 x 3.3 mm footprint) ٠
- Low thermal resistance
- Low 0.8 mm profile •

## 3. Applications

• Active clamp circuits

## 4. Quick reference data

Table 1. Quicl	k reference data						
Symbol	Parameter	Conditions		Min	Тур	Мах	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-	-100	V
V <sub>GS</sub>	gate-source voltage	_		-20	-	20	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 25 °C	[1]	-	-	-1.4	А
Static charac	teristics						
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -1.4 A; T <sub>j</sub> = 25 °C		-	275	400	mΩ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.



# 5. Pinning information

Table 2	. Pinning info	rmation		
Pin	Symbol	Description	Simplified outline	Graphic symbol
1	S	source		D
2	S	source		
3	S	source		G ( F Y)
4	G	gate		s
5	D	drain		017aaa094
6	D	drain		
7	D	drain	MLPAK33 (SOT8002-2)	
8	D	drain		

# 6. Ordering information

Table 3. Ordering information	on
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Type number	Package					
	Name	Description	Version			
PXP400-100QS	MLPAK33	plastic thermal enhanced surface mounted package; mini leads; 8 terminals; pitch 0.65 mm; 3.3 x 3.3 x 0.8 mm body	SOT8002-2			

# 7. Marking

Table 4. Marking codes	
Type number	Marking code
PXP400-100QS	8AL

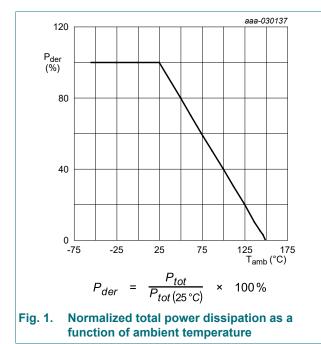
# 8. Limiting values

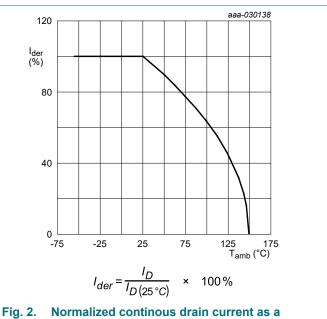
#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	T <sub>j</sub> = 25 °C		-	-100	V
V <sub>GS</sub>	gate-source voltage	_		-20	20	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 25 °C	[1]	-	-1.4	А
		V <sub>GS</sub> = -10 V; T <sub>amb</sub> = 100 °C	[1]	-	-0.9	A
		V <sub>GS</sub> = -10 V; T <sub>sp</sub> = 25 °C		-	-3.5	А
I <sub>DM</sub>	peak drain current	$T_{amb}$ = 25 °C; single pulse; $t_p \le 10 \ \mu s$		-	-6	А
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = 25 °C	[1]	-	1.7	W
		T <sub>sp</sub> = 25 °C		-	10.4	W
Tj	junction temperature			-55	150	°C
T <sub>amb</sub>	ambient temperature			-55	150	°C
T <sub>stg</sub>	storage temperature			-65	150	°C
Source-drain	n diode		I	I		
ls	source current	T <sub>amb</sub> = 25 °C	[1]	-	-1.4	А
Avalanche r	uggedness			I		
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$T_{j(init)} = 25 \text{ °C; } I_D = -0.58 \text{ A; DUT in}$ avalanche (unclamped)		-	28	mJ

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.



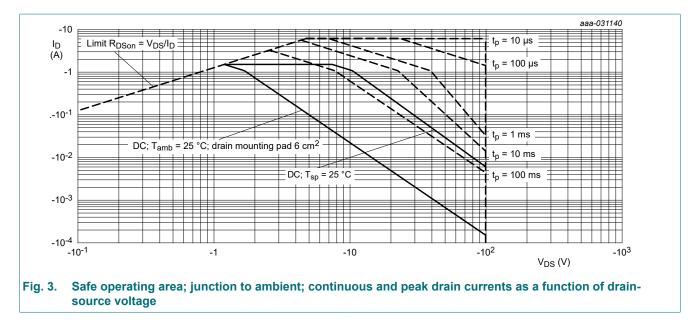




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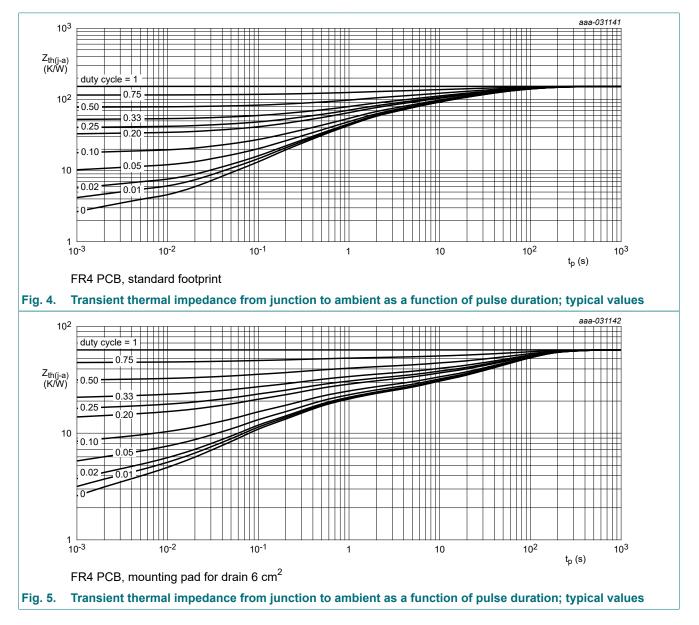
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# 9. Thermal characteristics

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
R <sub>th(j-a)</sub>	thermal resistance from	in free air	[1]	-	155	195	K/W
junction to ambient		[2]	-	60	75	K/W	
R <sub>th(j-sp)</sub>	thermal resistance from junction to solder point			-	10	12	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and mounting pad for drain 6 cm<sup>2</sup>.



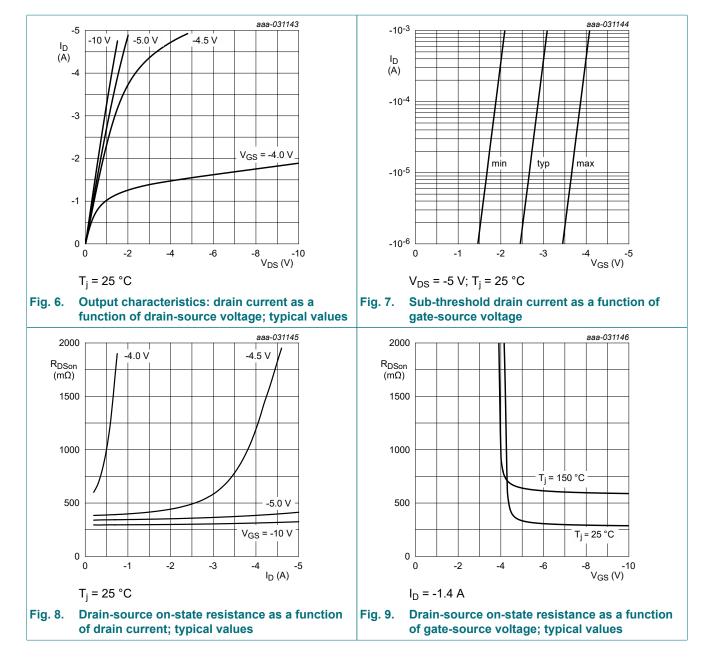
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# **10. Characteristics**

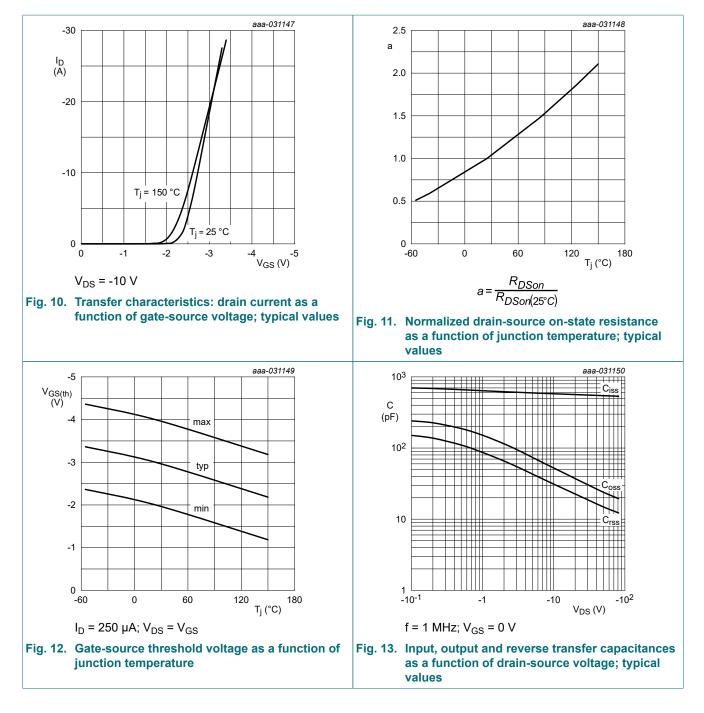
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	cteristics					
V <sub>(BR)DSS</sub>	drain-source breakdown voltage	I <sub>D</sub> = -250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-100	-	-	V
V <sub>GSth</sub>	gate-source threshold voltage	$I_D$ = -250 µA; $V_{DS}$ = $V_{GS}$ ; $T_j$ = 25 °C	-2	-3	-4	V
I <sub>DSS</sub>	drain leakage current	V <sub>GS</sub> = 0 V; V <sub>DS</sub> = -100 V; T <sub>j</sub> = 25 °C	-	-	-1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	-100	nA
		V <sub>GS</sub> = 20 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-	100	nA
R <sub>DSon</sub>	drain-source on-state	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -1.4 A; T <sub>j</sub> = 25 °C	-	275	400	mΩ
	resistance	V <sub>GS</sub> = -10 V; I <sub>D</sub> = -1.4 A; T <sub>j</sub> = 150 °C	-	580	844	mΩ
		V <sub>GS</sub> = -6 V; I <sub>D</sub> = -1.1 A; T <sub>j</sub> = 25 °C	-	290	600	mΩ
9 <sub>fs</sub>	forward transconductance	V <sub>DS</sub> = -10 V; I <sub>D</sub> = -1.4 A; T <sub>j</sub> = 25 °C	-	3.9	-	S
R <sub>G</sub>	gate resistance	f = 1 MHz	-	12	-	Ω
Dynamic ch	aracteristics					
Q <sub>G(tot)</sub>	total gate charge	$V_{DS}$ = -50 V; I <sub>D</sub> = -1.4 A; V <sub>GS</sub> = -10 V; T <sub>j</sub> = 25 °C	-	10.1	15.2	nC
		V <sub>DS</sub> = -50 V; I <sub>D</sub> = -1.1 A; V <sub>GS</sub> = -6 V;	-	6.4	9.6	nC
Q <sub>GS</sub>	gate-source charge	T <sub>j</sub> = 25 °C	-	1.9	-	nC
Q <sub>GD</sub>	gate-drain charge	1 – – – – – – – – – – – – – – – – – – –	-	2.6	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = -50 V; f = 1 MHz; V <sub>GS</sub> = 0 V;	-	544	-	pF
C <sub>oss</sub>	output capacitance	T <sub>j</sub> = 25 °C	-	25	-	pF
C <sub>rss</sub>	reverse transfer capacitance		-	15	-	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS}$ = -50 V; I <sub>D</sub> = -1.1 A; V <sub>GS</sub> = -4.5 V;	-	12	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 °C$	-	36	-	ns
t <sub>d(off)</sub>	turn-off delay time	1	-	9	-	ns
t <sub>f</sub>	fall time	1	-	14	-	ns
Source-drai	n diode	· · ·				
V <sub>SD</sub>	source-drain voltage	I <sub>S</sub> = -1.4 A; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	-0.8	-1.2	V
t <sub>rr</sub>	reverse recovery time	I <sub>S</sub> = -1.4 A; dI <sub>S</sub> /dt = -100 A/µs;	-	27	-	ns
Q <sub>r</sub>	recovered charge	V <sub>GS</sub> = -4.5 V; V <sub>DS</sub> = -40 V; T <sub>j</sub> = 25 °C	-	32	-	nC

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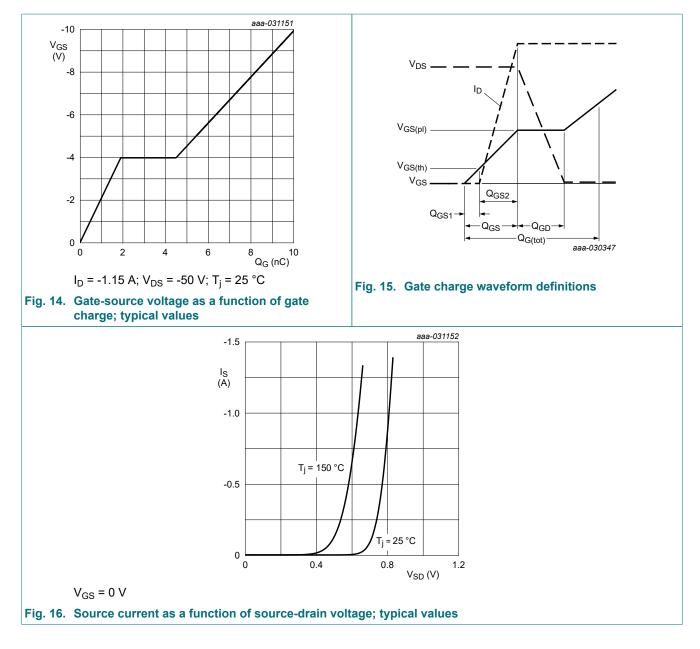
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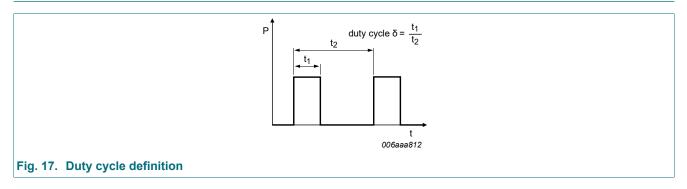


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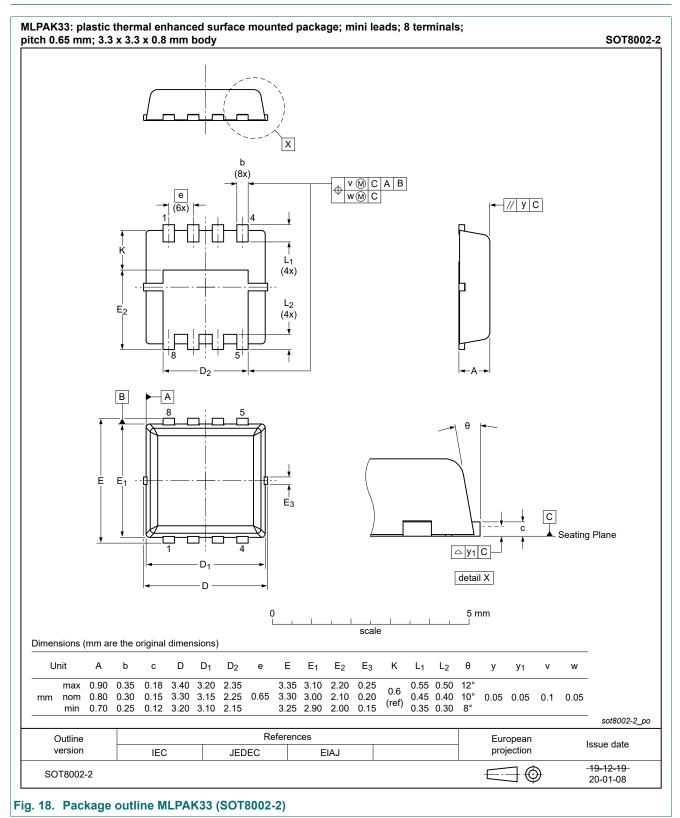


## 11. Test information



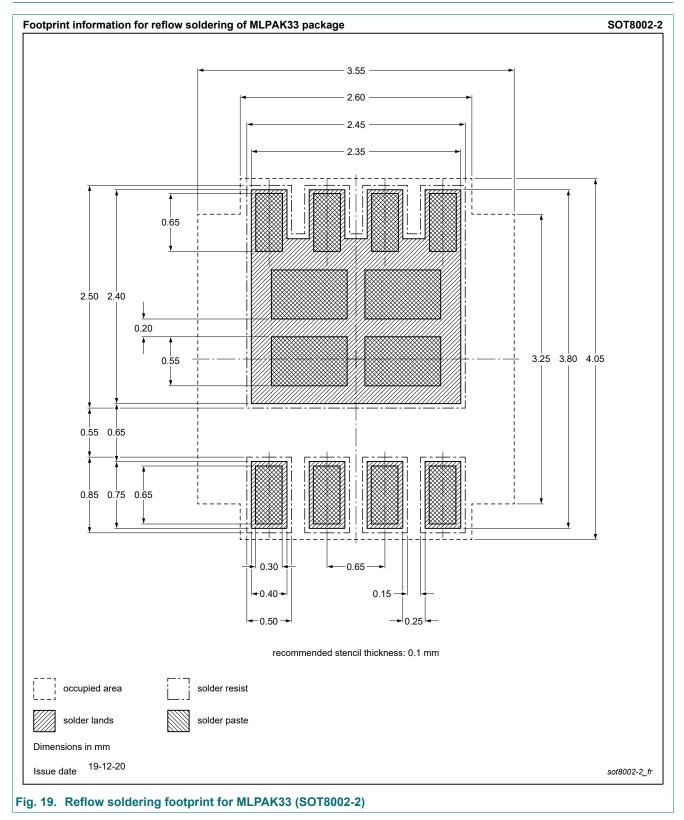
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## 12. Package outline



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# 13. Soldering



# 14. Revision history

Table 8. Revision history						
Data sheet ID	Release date	Data sheet status	Change notice	Supersedes		
PXP400-100QS v.1	20200507	Product data sheet	-	-		

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## 15. Legal information

#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

 Please consult the most recently issued document before initiating or completing a design.

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